Div. of Se (Rev. 8-88) Attorney Docket No. U.S. Department of Commerce Form PTO-1449 No. 08/9 1508.63671 Patent and Trademark Office INFORMATION DISCLOSURE CITATION (Use several sheets if necessary) Applicant Shigeru Okamoto **Group 2823** Filing Date 10/29/97 U.S. PATENT DOCUMENTS Class Subclass Filing Date Name Date Examiner Document No. initial* 71 Apr. 14, 1989 357 Nishida 4,990,997 Feb. 5, 1991 180 May 18, 1990 437 Stevens 5,070,036 Dec. 3, 1991 Aug. 6, 1992 437 194 Mar. 1, 1994 Hayasaka et al. 5,290,733 Feb. 6, 1995 576 Fine et al. 427 Nov. 7, 1995 5.464.666 Aug. 1, 1994 60 Nishioka et al. 437 Feb. 6, 1996 5,489,548 192 Dec. 10, 1993 437 Lee 5,552,341 Sep. 3, 1996 Aug. 1, 1994 257 530 Forouhi et al. Mar. 25, 1997 5,614,756 192 Dec. 8, 1995 Shinriki et al. 437 May 6, 1997 5,627,102 Dec. 5, 1994 Tamura et al. 257 530 Jun. 24, 1997 5,641,985 751 Dec. 8, 1995 257 Jul. 29, 1997 Liao et al. 5,652,464 635 Sep. 10, 1996 257 Chiang et al. Apr. 14, 1998 5,739,579 -Jun. 7, 1995 55 Aug. 11, 1998 257 Summerfelt 5,793,057 627 Sep. 10, 1996 438 Sep. 1, 1998 Huang et al. 5,801,095 Sep. 3, 1996 653 438 Fiordalice et al. 5,801,098 Sep. 1, 1998 751 Jul. 9, 1996 257 lijima et al. May 11, 1999 5,903,053 FOREIGN PATENT DOCUMENTS OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.) John A.T. Norman, David A. Roberts et al., ENHANCED DEPOSITION OF COPPER FILMS BY CVD -Advanced Metalization for ULSI Application pp. 57-62 Susan L. Cohen, Michael Liehr and Srinandan Kasi, Mechanisms of copper chemical vapor depositions, Appl. Phys. Lett. 60 (1), January 6, 1992, pp. 50-52 **Date Considered** Examiner

*Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation

if not in conformance and not considered. Include copy of this form with next communication to applicant.

3